

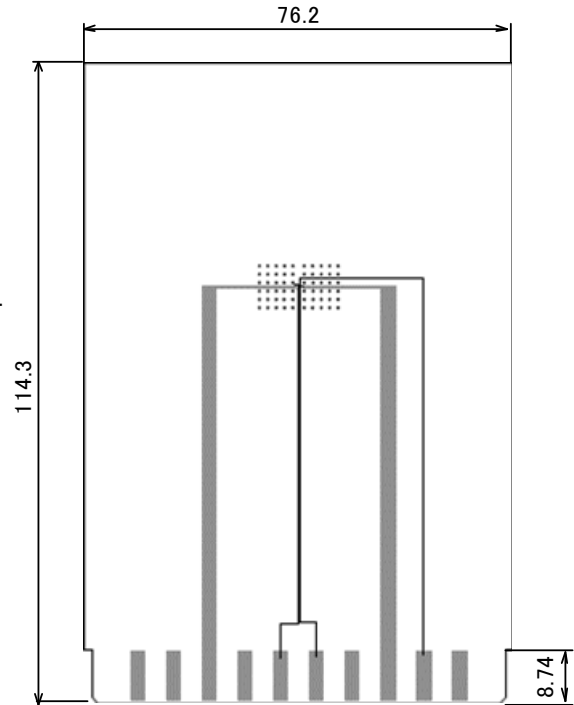
● **WLP-5-06 Power Dissipation (JESD51-7)**

Power dissipation data for the WLP-5-06 is shown in this page.
 The value of power dissipation varies with the mount board conditions.
 Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

- Condition : Mount on a board
- Ambient : Natural convection
- Soldering : Lead (Pb) free
- Board : The board using 4 copper layer.
 (76.2mm × 114.3mm ••• Area: about 8700mm²)
- 1st layer※ : No copper foil (Signal layer)
- 2nd layer : 70mm × 70mm_Connected to heat-sink.
- 3rd layer : 70mm × 70mm_Connected to heat-sink.
- 4th layer : No copper foil (Signal layer)
- Material : Glass Epoxy(FR-4)
- Thickness : 1.6mm
- Through-hole ϕ 0.2mm x 60pcs

※The copper layer thickness is 35 μ m, caused by signal layer pattern.



2. Power Dissipation vs. Ambient temperature

Board Mount($T_{jmax} = 125^{\circ}C$)

Ambient Temperature ($^{\circ}C$)	Power Dissipation Pd (mW)	$\theta_{ja} (^{\circ}C/W)$
25	500	200.00
105	100	

